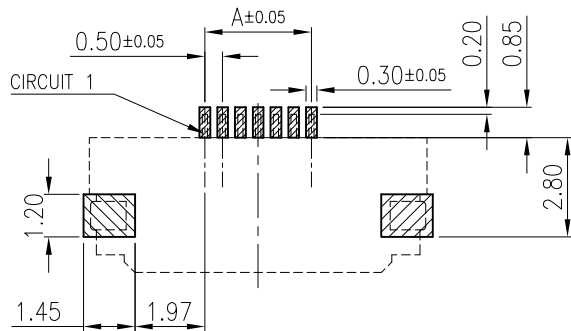
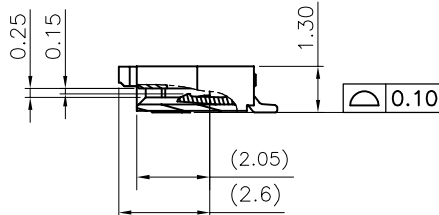
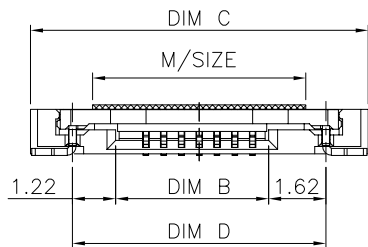
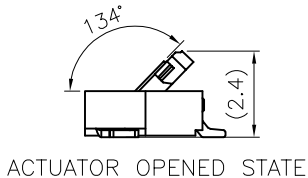
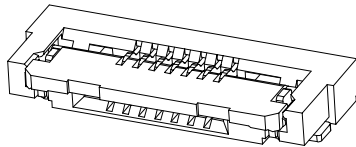
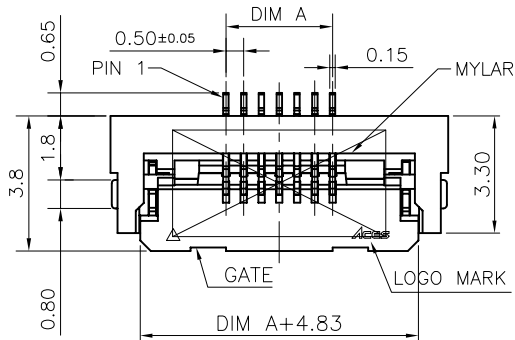
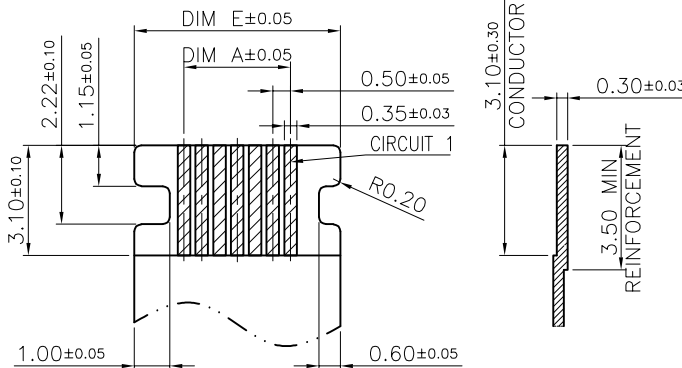




A B C D E F



RECOMMENDED PC BOARD PATTERN DIM.(REF.)



APPLICABLE FPC RECOMMENDED DIM. (THICKNESS: 0.3±0.03)

NOTES:

1. MATERIAL:

- 1.1 HOUSING: THERMOPLASTIC, HIGH TEMP.,UL94V-0; COLOR:NATURAL.
- 1.2 ACTUATOR: THERMOPLASTIC, HIGH TEMP.,UL94V-0; COLOR:BLACK.
- 1.3 CONTACT: COPPER ALLOY
- 1.4 FITTING NAIL: COPPER ALLOY

2. FINISH:

2.1 CONTACT:

- 50u" MIN. NICKEL PLATING OVER ALL,
- 1:GOLD FLASH PLATING ON CONTACT AND SOLDER AREA;
- C:15u"MIN. GOLD PLATING ON CONTACT AREA AND GOLD FLASH ON SOLDER AREA
- A:3u"MIN. GOLD PLATING ON CONTACT AREA AND GOLD FLASH ON SOLDER AREA

2.2 FITTING NAIL:50u" MIN. NICKEL UNDERPLATING OVERALL, 100~200u" MATT TIN PLATING.

- 3. REFLOW SOLDER CAPABLE TO 260°C PER ACES SPEC.
- 4. SPEC. PLS. REFER TO PS-51580-XXXXX-XXX.
- 5. PACKAGE PLS. REFER TO 51580-XXXXX-00-TRP.
- 6. PART NUMBER

51580-XXX X X-XXX

NO OF CKT	HOUSING MATERIAL&COLOR	ACTUATOR MATERIAL&COLOR	HALOGEN FREE
	001 HF PLASTIC & NATURAL	HF PLASTIC & BLACK	HF

- PACKING
- 0: TAPE & REEL
 - 1: TUBE
 - 4: TAPE & REEL WITH MYLAR
 - 5: TUBE WITH MYLAR

- PLATING
- 1: GOLD FLASH PLATING ON CONTACT AND SOLDER AREA
 - C:15u"MIN.GOLD PLATING ON CONTACT AREA
 - A:3u"MIN.GOLD PLATING ON CONTACT AREA

CKT	Dim A	Dim B	Dim C	Dim D	Dim E	M/s(W)
6	2.50	3.80	9.00	6.63	5.30	6.00
11	5.00	6.30	11.50	9.13	7.80	6.00
12	5.50	6.80	12.00	9.63	8.30	6.00
32	15.50	16.80	22.00	19.63	18.30	6.00

一般公差 TOLERANCES X ±0.50 .XX ±0.15 X ±0.25 .XXX ±0.10 ANGLES ±2°		宏致電子股份有限公司 Aces Electronics Co.,Ltd.	
檢驗尺寸標示 SYMBOLS INDICATE CLASSIFICATION MARK IS CRITICAL DIM. MARK IS MAJOR DIM.	品名 (TITLE) 0.5 PITCH EASY ON FPC CONN H=1.3mm SMT R/A TYPE	製圖 (DR) 22/07/26 Xu,Bin 審核 (CHKD) Xu,ZhiYong 核准 (APPD) Xu,ZhiYong	圖號 (DWG NO.) 51580-XXXXX-XXX
表面處理 (FINISH)	比例 (SCALE) 3:1	單位 (UNITS) mm	張數 (SHEET) 1 OF 1 圖號 (DWG NO.) 51580-XXXXX-XXX

A B C D E F